

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

JT6J15A-AS

ROW DRIVER FOR A DOT MATRIX LCD

The JT6J15A-AS is a 80-channel-output row driver for a STN dot matrix LCD. The JT6J15A-AS features 28 V LCD drive voltage. The JT6J15A-AS is able to drive LCD panels with a duty ratio of up to 1/160.

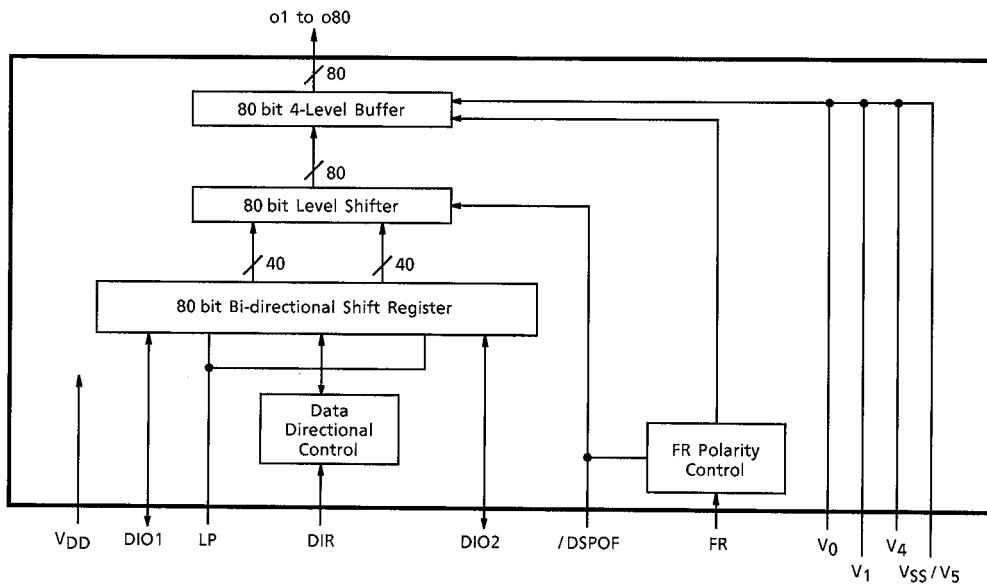
As the JT6J15A-AS is equipped with a built-in voltage divider resistor, power supply operation amplifier, four and six-fold booster circuit, a contrast control circuit and a booster oscillator (oscillating capacitance is built in, and oscillating resistance is attached externally,) it is easy to structure a low power consumption LCD system by combining it with the JT6J14-AS column driver.

Features

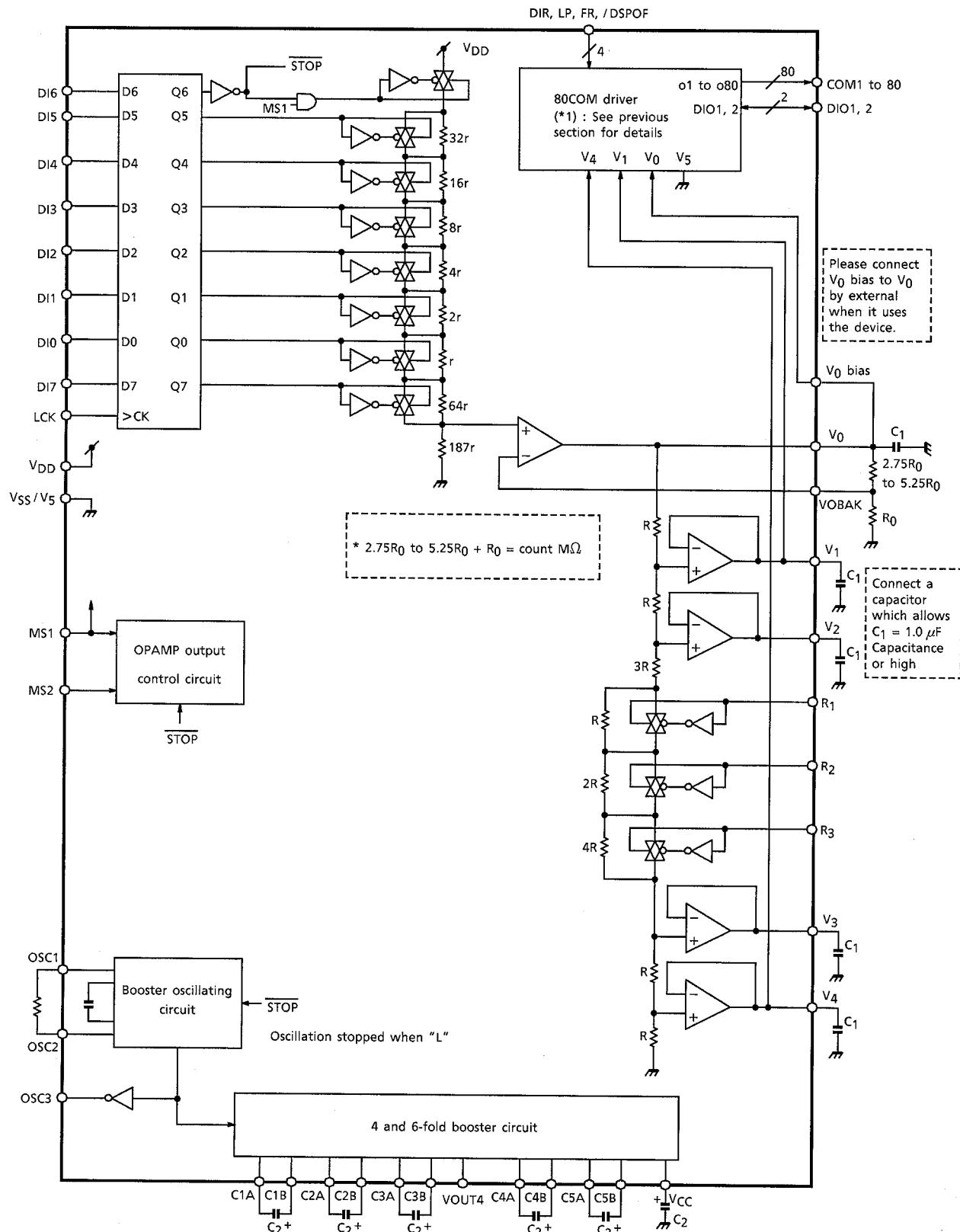
- Display duty application : to 1/160
- LCD drive signal : 80
- Data transfer : Two different styles of 1-bit bidirectional can be selected
 - (1) COM80 ← COM1
 - (2) COM80 → COM1
- Operating temperature : -20 to 75°C
- LCD drive output resistance: 1.5 kΩ Max (Vo = 12.8 V, 1/7 to 1/14 bias)
- Display-off function : When /DSPOF is "L", all LCD drive outputs (o1 to o80) remain at the VSS/V5 level
- LCD drive voltage : 11 to 28 V (maximum drive voltage = 30 V)
- Power supply voltage : 2.7 to 5.5 V

Block Diagram 1

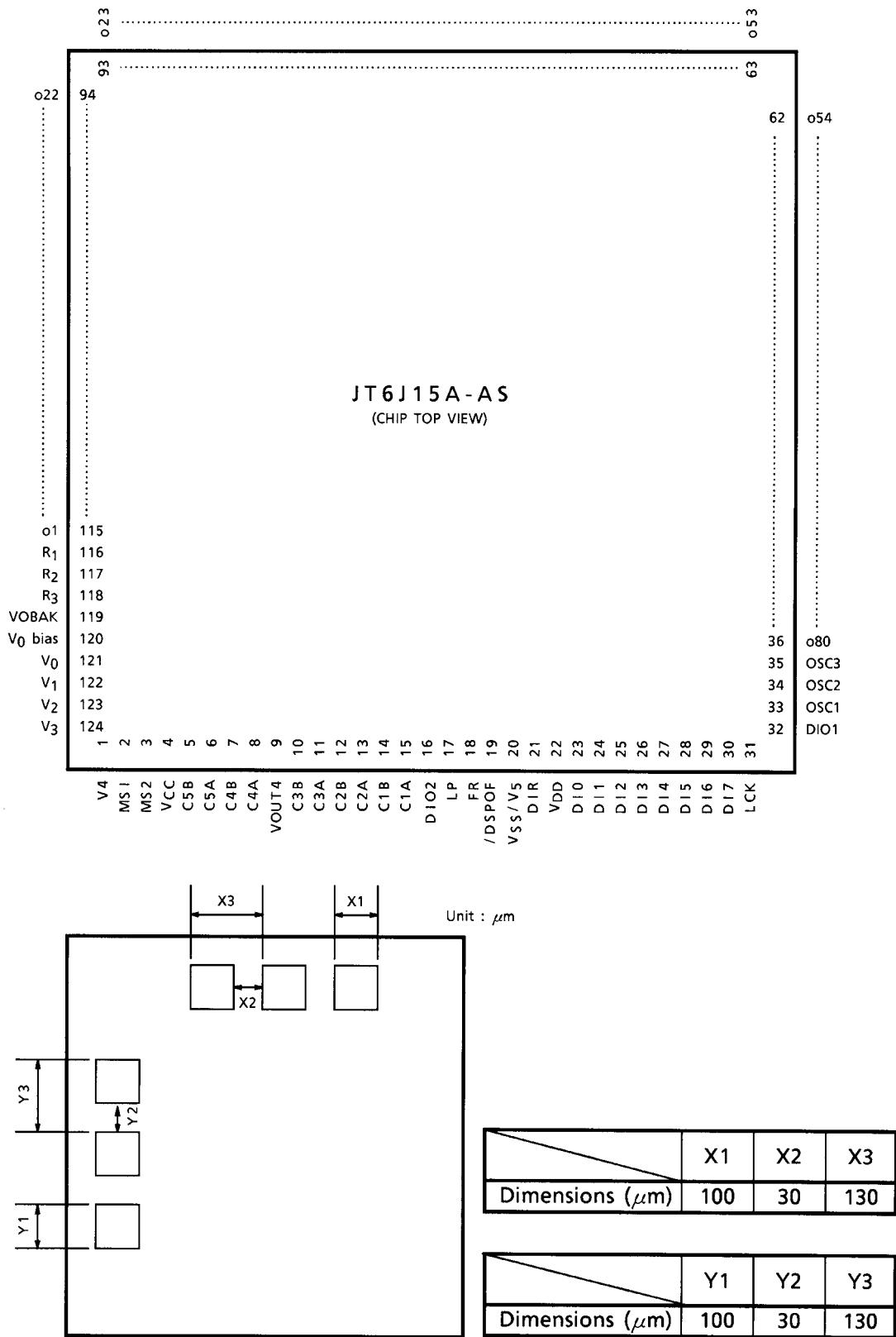
*1…80 COM driver area



Block Diagram 2



Pin Assignment



Pad Coordinates

Scribe width : $80 \times 140 \mu\text{m}$
 Chip size : $4790 \times 4850 \mu\text{m}$ (Including scribe width)
 Number of PAD : 124 pcs
 PAD size : $100 \mu\text{m} \square$
 Palette edge coordinates 1: -2355, -2355 Chip edge coordinates 1: -2395, -2425
 2: -2355, 2355 2: -2395, 2425
 3: 2355, 2355 3: 2395, 2425
 4: 2355, -2355 4: 2395, -2425

[Unit: μm]

No	Pad Name	X Point	Y Point
1	V ₄	-1950	-2139
2	MS1	-1820	-2139
3	MS2	-1690	-2139
4	V _{CC}	-1560	-2139
5	C5B	-1430	-2139
6	C5A	-1300	-2139
7	C4B	-1170	-2139
8	C4A	-1040	-2139
9	VOUT4	-910	-2139
10	C3B	-780	-2139
11	C3A	-650	-2139
12	C2B	-520	-2139
13	C2A	-390	-2139
14	C1B	-260	-2139
15	C1A	-130	-2139
16	DIO2	0	-2139
17	LP	130	-2139
18	FR	260	-2139
19	/ DSPOF	390	-2139
20	V _{SS} / V ₅	520	-2139
21	DIR	650	-2139
22	V _{DD}	780	-2139
23	DIO	910	-2139
24	DI1	1040	-2139
25	DI2	1170	-2139
26	DI3	1300	-2139
27	DI4	1430	-2139
28	DI5	1560	-2139
29	DI6	1690	-2139
30	DI7	1820	-2139
31	LCK	1950	-2139
32	DIO1	2139	-1950
33	OSC1	2139	-1820

No	Pad Name	X Point	Y Point
34	OSC2	2139	-1690
35	OSC3	2139	-1560
36	o80	2139	-1430
37	o79	2139	-1300
38	o78	2139	-1170
39	o77	2139	-1040
40	o76	2139	-910
41	o75	2139	-780
42	o74	2139	-650
43	o73	2139	-520
44	o72	2139	-390
45	o71	2139	-260
46	o70	2139	-130
47	o69	2139	0
48	o68	2139	130
49	o67	2139	260
50	o66	2139	390
51	o65	2139	520
52	o64	2139	650
53	o63	2139	780
54	o62	2139	910
55	o61	2139	1040
56	o60	2139	1170
57	o59	2139	1300
58	o58	2139	1430
59	o57	2139	1560
60	o56	2139	1690
61	o55	2139	1820
62	o54	2139	1950
63	o53	1950	2139
64	o52	1820	2139
65	o51	1690	2139
66	o50	1560	2139

No	Pad Name	X Point	Y Point
67	o49	1430	2139
68	o48	1300	2139
69	o47	1170	2139
70	o46	1040	2139
71	o45	910	2139
72	o44	780	2139
73	o43	650	2139
74	o42	520	2139
75	o41	390	2139
76	o40	260	2139
77	o39	130	2139
78	o38	0	2139
79	o37	-130	2139
80	o36	-260	2139
81	o35	-390	2139
82	o34	-520	2139
83	o33	-650	2139
84	o32	-780	2139
85	o31	-910	2139
86	o30	-1040	2139
87	o29	-1170	2139
88	o28	-1300	2139
89	o27	-1430	2139
90	o26	-1560	2139
91	o25	-1690	2139
92	o24	-1820	2139
93	o23	-1950	2139
94	o22	-2139	1950
95	o21	-2139	1820

No	Pad Name	X Point	Y Point
96	o20	-2139	1690
97	o19	-2139	1560
98	o18	-2139	1430
99	o17	-2139	1300
100	o16	-2139	1170
101	o15	-2139	1040
102	o14	-2139	910
103	o13	-2139	780
104	o12	-2139	650
105	o11	-2139	520
106	o10	-2139	390
107	o9	-2139	260
108	o8	-2139	130
109	o7	-2139	0
110	o6	-2139	-130
111	o5	-2139	-260
112	o4	-2139	-390
113	o3	-2139	-520
114	o2	-2139	-650
115	o1	-2139	-780
116	R ₁	-2139	-910
117	R ₂	-2139	-1040
118	R ₃	-2139	-1170
119	VOBAK	-2139	-1300
120	V ₀ bias	-2139	-1430
121	V ₀	-2139	-1560
122	V ₁	-2139	-1690
123	V ₂	-2139	-1820
124	V ₃	-2139	-1950

Pin Functions

Pin Name	I / O	Functions	Level
o1 to o80	Output	Output for LCD drive signal	V_0 to V_{SS} / V_5
DIO1, DIO2	I / O	Input / Output for shift data	
LP	Input	(Shift Clock Pulse) Input for shift clock pulse	
FR	Input	(Frame) Input for frame signal	
DIR	Input	(Direction) Input for data flow direction select	
/ DSPOF	Input	(Display Off) Display off pin “L”: Display-off mode, (o1 to o80) remain at the V_{SS} / V_5 level. “H”: Display-on mode, (o1 to o80) are operational.	
DI0 to DI7	Input	Data bus: For contrast control usage Contrast adjustments are variable between 128 stages with the DI0 to DI5 and D17 data. DI6: When “H”: Stops the booster's oscillation frequency and turns the power supply (V_{DD}) to the contrast controller off When “L”: Operates the booster circuit and contrast controller circuit	
LCK	Input	Data bus loading clock Synchronized during rising and loaded internally.	
R1 to R3	Input	Bias set-up pin (bias settings possible between 1 / 7 and 1 / 14)	
OSC1 / OSC2	Input	Booster oscillation pin Resistors connected to these pins when the internal clock is operating (100 kΩ between OSC1 and OSC2). The clock is input to OSC1 when the external clock is operating.	
OSC3	Output	Booster oscillating output pin The OCS3 pin is connected to another IC's OCS1 when the booster's oscillating frequency is shared with multiple connections.	
MS1 / MS2	Input	Master / slave switching pin	—
CnA to CnB	—	Terminal for connecting external condensers (n = 1 to 5) Connect a booster capacitor which allows about $C_2 = 3.3 \mu F$ capacitance between CnA and CnB.	
VOUT4	—	Booster voltage output pin (4-fold booster) Connect VOUT4 and V_{CC} when use of 4-fold booster.	
V_{CC}	—	LCD drive voltage pin (operation amplifier drive voltage, 6-fold booster terminal)	
V_{DD}	—	Power supply for internal logic	
V_{SS} / V_5	—	Power supply for internal logic	
VOBAK	—	Voltage amplifier circuit	—
$V_0, V_1, V_2,$ $V_3, V_4,$ V_0 bias	—	Power supply for LCD drive circuit Connect an external capacitor which allows $C_1 = 1.0 \mu F$ capacitance or high to AMP output.	

Relationship Between FR, Data Input and Output Levels

FR	Input Data (Dio1, Dio2)	/ Dspof	Output Level
H	L	H	V_4
H	H	H	V_0 bias
L	L	H	V_1
L	H	H	V_{SS} / V_5
(Note)	(Note)	L	V_{SS} / V_5

Note: Don't Care

Data Input Format

DIR	Data Transfer Direction	Data Input terminals	
		DIO1	DIO2
H	$o_1 \rightarrow o_{80}$	Input	Output
L	$o_{80} \rightarrow o_1$	Output	Input

Operation Amplifier Output Control Circuit

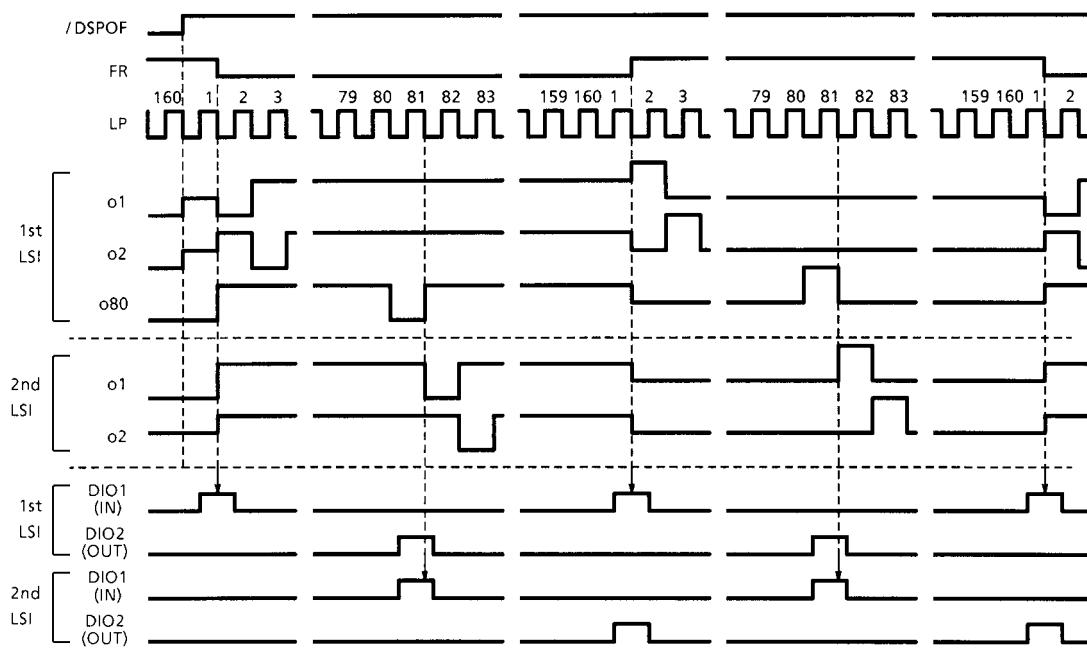
MS1	MS2	/ Stop	Mode	Booster Oscillations	Booster	V_0 Output	V_1, V_4 Output	V_2, V_3 Output
L	(Note 1)	L	Slave mode (The booster circuit is driven and V_{CC} voltage generated. V_0, V_1, V_2, V_3 and V_4 are supplied from an external source)	—	Booster stopped	Output CUT, PD Tr ON		Output CUT, PD Tr ON
		H		External clock	Booster stopped	Output CUT, PD Tr OFF (supplied from external source)		Output CUT, PD Tr ON
H	L	L	Master mode 1 (V_0 is output from the V_{CC} voltage generating through driving the booster circuit. V_1, V_2, V_3 and V_4 are supplied from an external source)	Oscillations stopped	Booster stopped	V_0 Output, PD Tr ON	V_1, V_4 Output, PD Tr ON	Output CUT, PD Tr ON
		H		Oscillations operating	Booster operating	Output ON, PD Tr OFF (supplied to internal / external sources)	Output cut, PD Tr OFF (supplied from external source)	Output CUT, PD Tr ON
H	H	L	Master mode 2 V_0, V_1, V_2, V_3 and V_4 are output from the V_{CC} voltage generating through driving the booster circuit.)	Oscillations stopped	Booster stopped	Output CUT, PD Tr ON		Output CUT, PD Tr ON
		H		Oscillations operating	Booster operating	Output ON, PD Tr OFF (supplied to internal / external sources)		Output ON, PD Tr OFF (supplied to external source)

PD: Pull Down

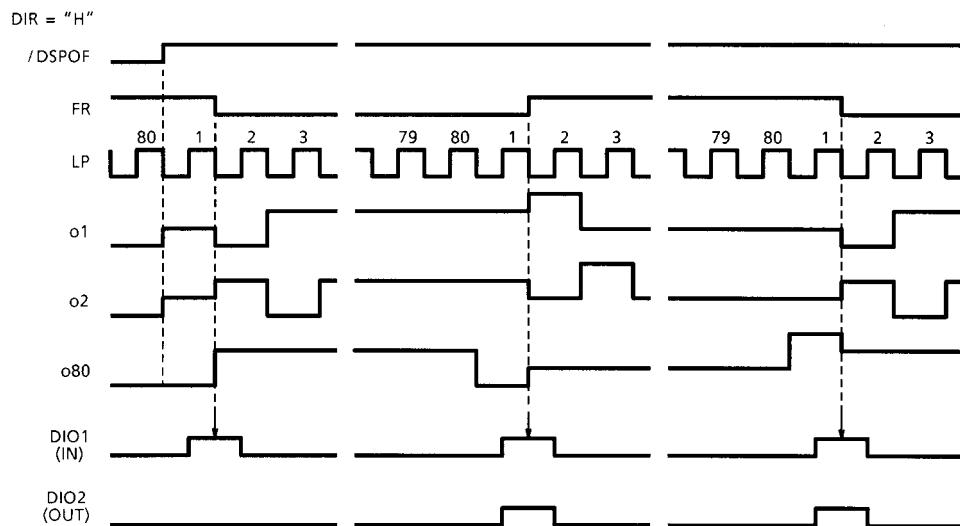
Note 1: Connect to V_{DD} or V_{SS} / V_5

Timing Diagram

- Use of JT6J15A-AS 2 pcs (DIR = "H")



- Use of JT6J15A-AS 1 pc (DIR = "H")



Absolute Maximum Ratings

(Ensure that the Following Conditions are Maintained, $V_0 \geq V_1 \geq V_2 \geq V_3 \geq V_4 \geq V_{SS} / V_5 = 0 \text{ V}$)

Characteristic	Symbol	Rating	Unit	Pin Name
Power Supply Voltage (1)	V_{DD}	-0.3 to 6.0	V	V_{DD}
Power Supply Voltage (2)	V_{CC}	V_{DD} to 30.0	V	V_{CC}
Input Voltage	V_{in}	-0.3 to $V_{DD} + 0.3$	V	(Note 2)
Operating Temperature	T_{opr}	-20 to 75	°C	—
Storage Temperature	T_{stg}	-40 to 125	°C	—

Note 2: FR, LP, DIR, DIO1, DIO2, DI0 to DI7, LCK, R1 to R3, / DSPOF

Electrical Characteristics**DC Characteristics 1**(Unless Otherwise Noted, $V_{SS} = 0 \text{ V}$, $V_{DD} = 2.7 \text{ to } 5.5 \text{ V}$, $V_0 = 11 \text{ to } 28 \text{ V}$, $T_a = -20 \text{ to } 75^\circ\text{C}$)

Item	Symbol	Test Circuit	Test Condition		Min	Typ.	Max	Unit	Pin Name
Supply Voltage (1)	V_{DD}	—	—		2.7	5.0	5.5	V	V_{DD}
Supply Voltage (2)	V_0	—	$V_{CC} \geq V_0$		11	—	28	V	V_0
Supply Voltage (3)	V_{CC}	—	$V_{CC} \geq V_0$		11	—	28	V	V_{CC}
Input Voltage	"H" Level	V_{IH}	—	—	0.8 V_{DD}	—	V_{DD}	V	(Note 3)
	"L" Level	V_{IL}	—	—	0	—	0.2 V_{DD}		
Output Voltage	"H" Level	V_{OH}	—	$I_{OH} = -0.5 \text{ mA}$	$V_{DD} - 0.5$	—	V_{DD}	V	DIO1, DIO2
	"L" Level	V_{OL}	—	$I_{OL} = 0.5 \text{ mA}$	0	—	0.5		
Output Resistance	"H" Level	R_{OH}	—	$V_{OUT} = V_0 - 0.5 \text{ V}$ (Note 4)	—	—	1.5	kΩ	o1 to o80
	"M" Level	R_{OM}	—	$V_{OUT} = V_1 \pm 0.5 \text{ V}$ (Note 4)	—	—	1.5		
		R_{OM}	—	$V_{OUT} = V_4 \pm 0.5 \text{ V}$ (Note 4)	—	—	1.5		
	"L" Level	R_{OL}	—	$V_{OUT} = V_{SS} / V_5 + 0.5 \text{ V}$ (Note 4)	—	—	1.5		
Input Current	I_{IL1}	—	$V_{IN} = 0 \text{ to } V_{DD}$		-1.0	—	1.0	μA	(Note 3)
Output Voltage (with a 4-fold booster)	V_{O1}	—	$V_{DD} = 5.0 \text{ V}$ (Note 5)		17.64	—	—	V	V_{CC}
Output Voltage (with a 6-fold booster)	V_{O2}	—	$V_{DD} = 3.0 \text{ V}$ (Note 5)		14.0	—	—		
Current Consumption	$I_{DD \text{ OPE}}$	—	$V_{DD} = 5.0 \text{ V}$	When operating (Note 6)	—	1.1	1.5	mA	V_{DD}
		—	$V_{DD} = 3.0 \text{ V}$	When operating (Note 7)	—	1.2	1.8		
	$I_{DD \text{ LEAK}}$	—	$V_{DD} = 5.5 \text{ V}$	When no operating	—	—	1.0	μA	$V_0 \text{ bias}$
	$I_0 \text{ bias OPE}$	—	$V_0 = 15.0 \text{ V}$	When operating (Note 8)	—	1.0	25		
	$I_{CC \text{ LEAK}}$	—		When no operating (Note 9)	—	—	1.0		V_{CC}

Note 3: FR, LP, DIR, DIO1, DIO2, DI0 to DI7, LCK, R1 to R3, / DSPOF

Note 4: $V_0 = 12.8 \text{ V}$, 1 / 7 to 1 / 14 biasNote 5: ILoad = 450 μA, external $C_2 = 3.3 \mu\text{F}$, when using COM 1 pc $T_a = 25^\circ\text{C}$, OP-AMP ONNote 6: Oscillation resistance = 100 kΩ, DC / DC ON, OP-AMP ON, 1 / 10 bias, contrast Max fLP = 11.2 kHz, fFR = 35 Hz, fFP = 70 Hz, $V_{DD} = 5.0 \text{ V}$, 4 booster, no loadNote 7: Oscillation resistance = 100 kΩ, DC / DC ON, OP-AMP ON, 1 / 10 bias, contrast Max fLP = 11.2 kHz, fFR = 35 Hz, fFP = 70 Hz, $V_{DD} = 3.0 \text{ V}$, 6 booster, no load

Note 8: LCD drive current: fFR = 35 Hz, fLP = 11.2 kHz, fFP = 70 Hz, 1 / 10 bias, no load, MS1 = "L", / STOP = "L"

Note 9: MS1 = "L", / STOP = "L"

fFP: Screen switching frequency

DC Characteristics 2**Load Regulations Characteristics 1 ... No Load / Max Load Offset**

Test Conditions: $V_{CC} = 18 \text{ V}$ (Outside applied voltage), Contrast = 62 (DI1 to DI5 = "H", DI6, DI7 = "L"), External capacitor for AMP: $C_1 = 1.0 \mu\text{F}$
Gain Resistance = 4 times ($3R_0, R_0$), 1 / 10 bias, $V_{DD} = 5.0 \text{ V}$, $T_a = -20$ to 75°C , The V_1 to V_4 OFFSET spec is defined toward the ideal voltage calculated from the V_0 voltage.

Offset Specified Value

	No Load		Max Load		Max Load (Reverse Electric Current)		Unit
	Min	Max	Min	Max	Min	Max	
V_0	14.6	15.6	14.50	15.50	—	—	V
V_1	-100	90	-110	75	-110	110	mV
V_2	-65	65	-50	75	-110	110	mV
V_3	-70	70	-85	50	-110	110	mV
V_4	-55	50	-45	65	-110	110	mV
X	-220	190	-255	145	—	—	mV
Y	-120	130	-170	85	—	—	mV
ΔV	-210	190	-300	120	—	—	mV

Load Conditions

	No Load	Max Load	Max Load (Reverse Electric Current)	Unit
I_0	0	-300	—	μA
I_1	0	-50	50	μA
I_2	0	200	-100	μA
I_3	0	-200	100	μA
I_4	0	50	-50	μA

Non-lighting BIAS

$$X = (V_1 - V_2) - (V_0 - V_1)$$

$$Y = (V_3 - V_4) - (V_4 - V_{SS})$$

VOM balance

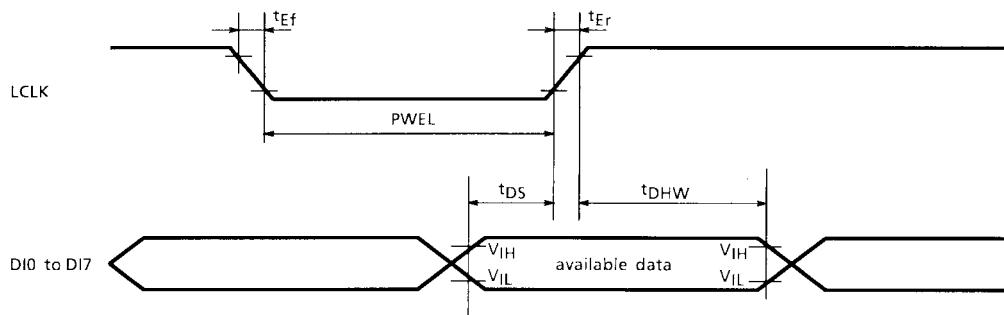
$$\Delta V = X + Y$$

V0 to V4 are Specified as Follows

When the V0 Voltage is Set to the maximum Voltage for the Contrast with the DI0 to DI7 Data Bus Set to "H".

Bias Set-Up Value	R ₁	R ₂	R ₃	V ₁	V ₂	V ₃	V ₄
1 / 7	H	H	H	6 / 7V0	5 / 7V0	2 / 7V0	1 / 7V0
1 / 8	L	H	H	7 / 8V0	6 / 8V0	2 / 8V0	1 / 8V0
1 / 9	H	L	H	8 / 9V0	7 / 9V0	2 / 9V0	1 / 9V0
1 / 10	L	L	H	9 / 10V0	8 / 10V0	2 / 10V0	1 / 10V0
1 / 11	H	H	L	10 / 11V0	9 / 11V0	2 / 11V0	1 / 11V0
1 / 12	L	H	L	11 / 12V0	10 / 12V0	2 / 12V0	1 / 12V0
1 / 13	H	L	L	12 / 13V0	11 / 13V0	2 / 13V0	1 / 13V0
1 / 14	L	L	L	13 / 14V0	12 / 14V0	2 / 14V0	1 / 14V0

Ac Characteristics 1



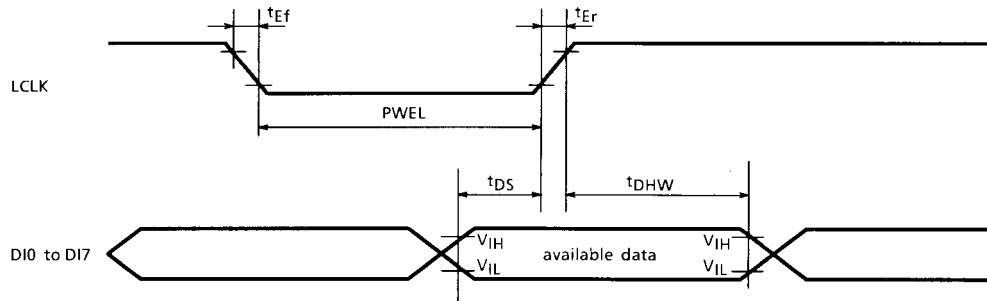
Test Conditions: t_c (One LP Signal Cycle) = $t_{CWH} + t_{CWL} + t_r + t_f$
 (Unless Otherwise Noted, $V_{SS} = 0$ V, $V_{DD} = 2.7$ to 5.5 V, $V_{CC} = 11$ to 28 V, $T_a = -20$ to 75°C)

Item	Symbol	Test Condition	Min	Typ.	Max	Unit
LP Pulse Width	t_{CWH}	LP	30	—	—	ns
	t_{CWL}	LP	1	—	—	μs
Data Set-up Time	t_{DSU}	DIO1, DIO2	30	—	—	ns
Data Hold Time	t_{DHD}	DIO1, DIO2	5	—	—	
LP Rise / Fall Time	t_r, t_f	LP, FR, DIO1, DIO2	—	—	50	
Output Delay Time (Note 11)	t_{pd}	DIO1, DIO2	20	—	500	
Oscillating Frequency	f_{osc}	OSC1 (Note 12)	25.5	—	42.5	kHz
External Clock Frequency		OSC3	25.5	—	42.5	

Note 11: $C_L = 10 \text{ pF}$

Note 12: External resistance = $100 \text{ k}\Omega$ (between OSC1 and OSC2)

AC Characteristics 2



Test Conditions 1

(Unless Otherwise Noted, $V_{SS} = 0 \text{ V}$, $V_{DD} = 3.0 \text{ V} \pm 10\%$, $V_{CC} = 11 \text{ to } 28 \text{ V}$, $T_a = -20 \text{ to } 75^\circ\text{C}$)

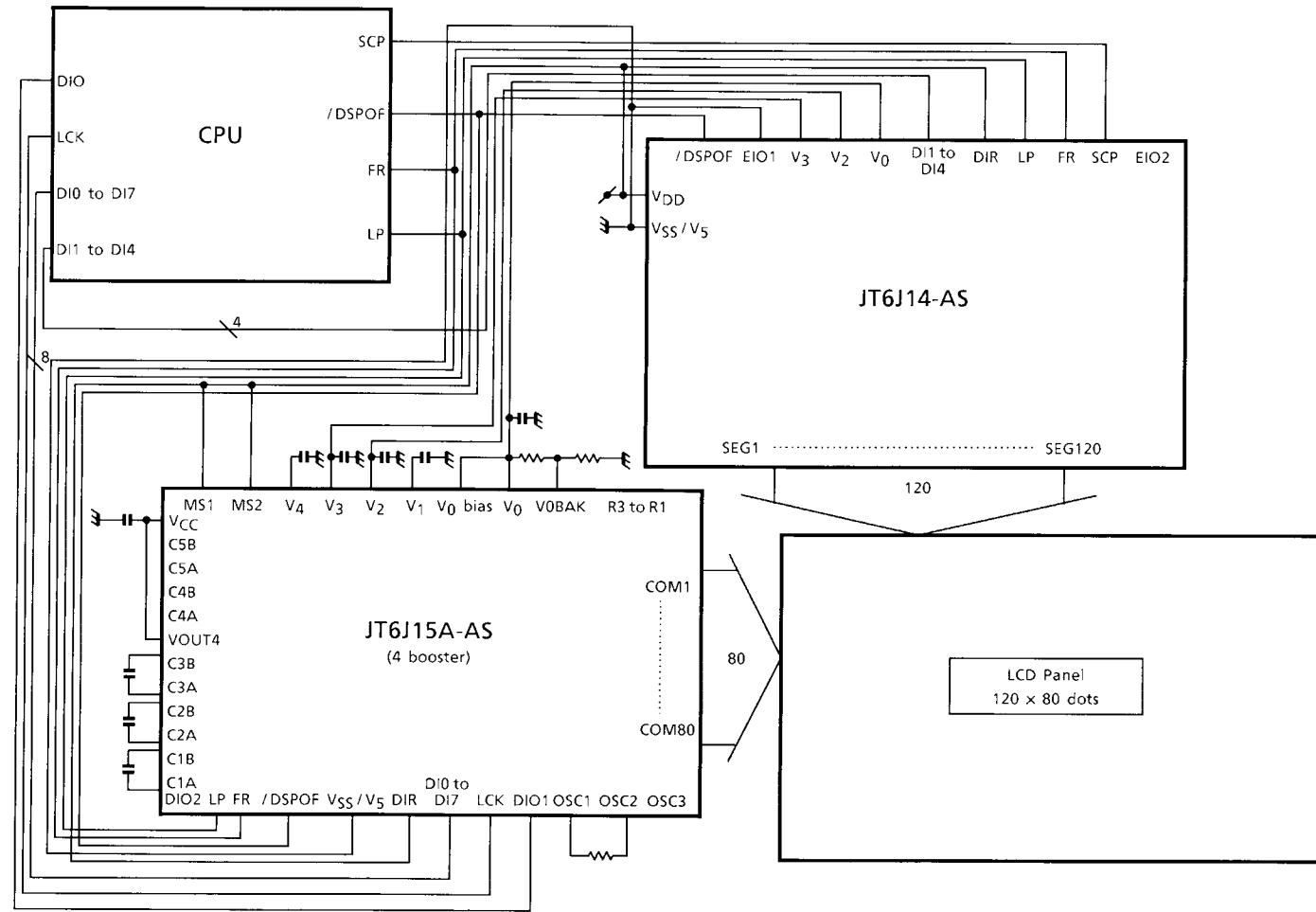
Item	Symbol	Test Condition	Min	Typ.	Max	Unit
Enable Rise / Fall Time	t_{Er} / t_{Ef}	—	—	—	25	ns
Enable Pulse Width	PWEL	—	60	—	—	ns
Data Set-up Time	t_{DS}	—	60	—	—	ns
Data Hold Time	t_{DHW}	—	10	—	—	ns

Test Conditions 2

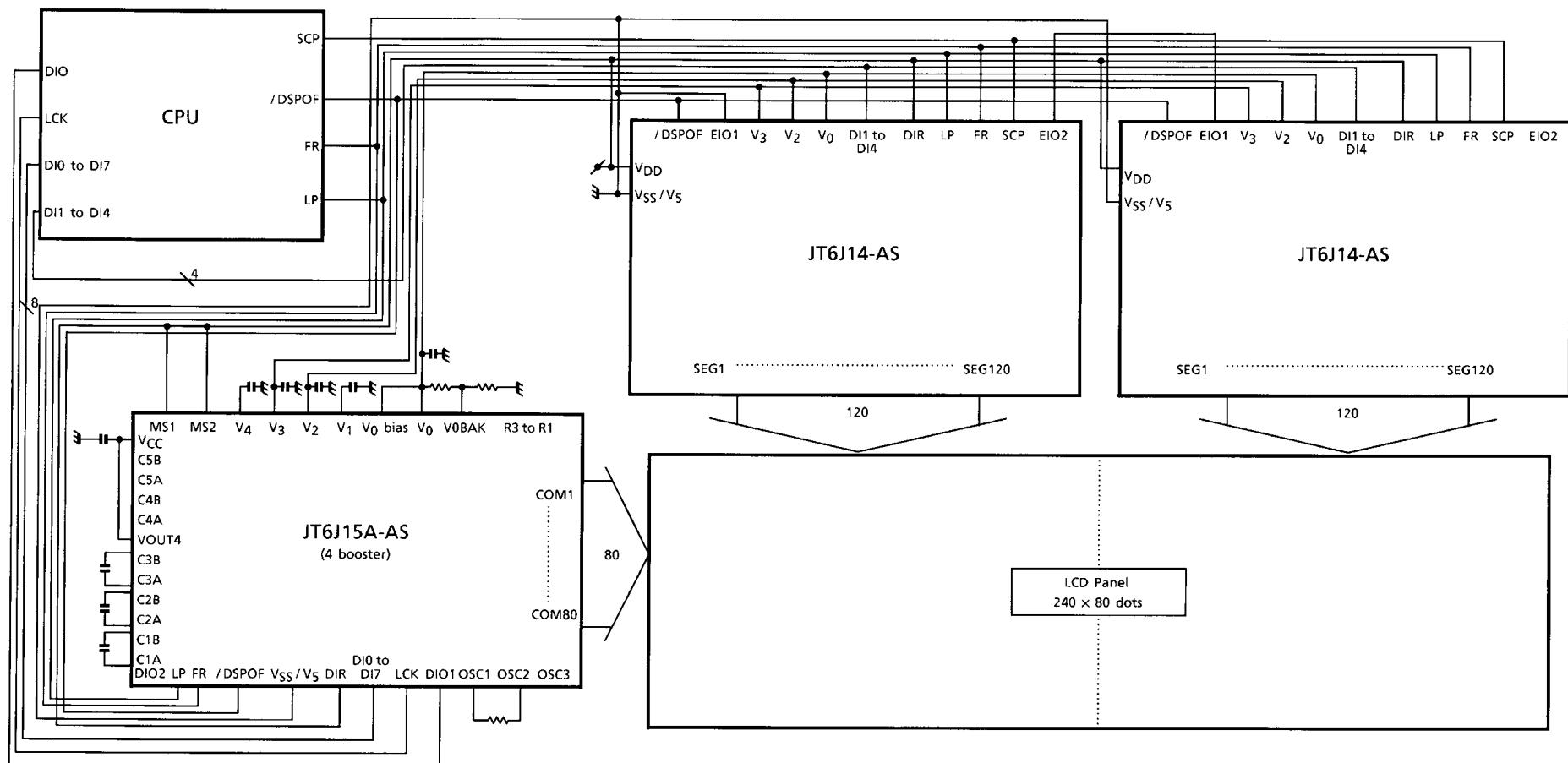
(Unless Otherwise Noted, $V_{SS} = 0 \text{ V}$, $V_{DD} = 5.0 \text{ V} \pm 10\%$, $V_{CC} = 11 \text{ to } 28 \text{ V}$, $T_a = -20 \text{ to } 75^\circ\text{C}$)

Item	Symbol	Test Condition	Min	Typ.	Max	Unit
Enable Rise / Fall Time	t_{Er} / t_{Ef}	—	—	—	20	ns
Enable Pulse Width	PWEL	—	60	—	—	ns
Data Set-up Time	t_{DS}	—	60	—	—	ns
Data Hold Time	t_{DHW}	—	10	—	—	ns

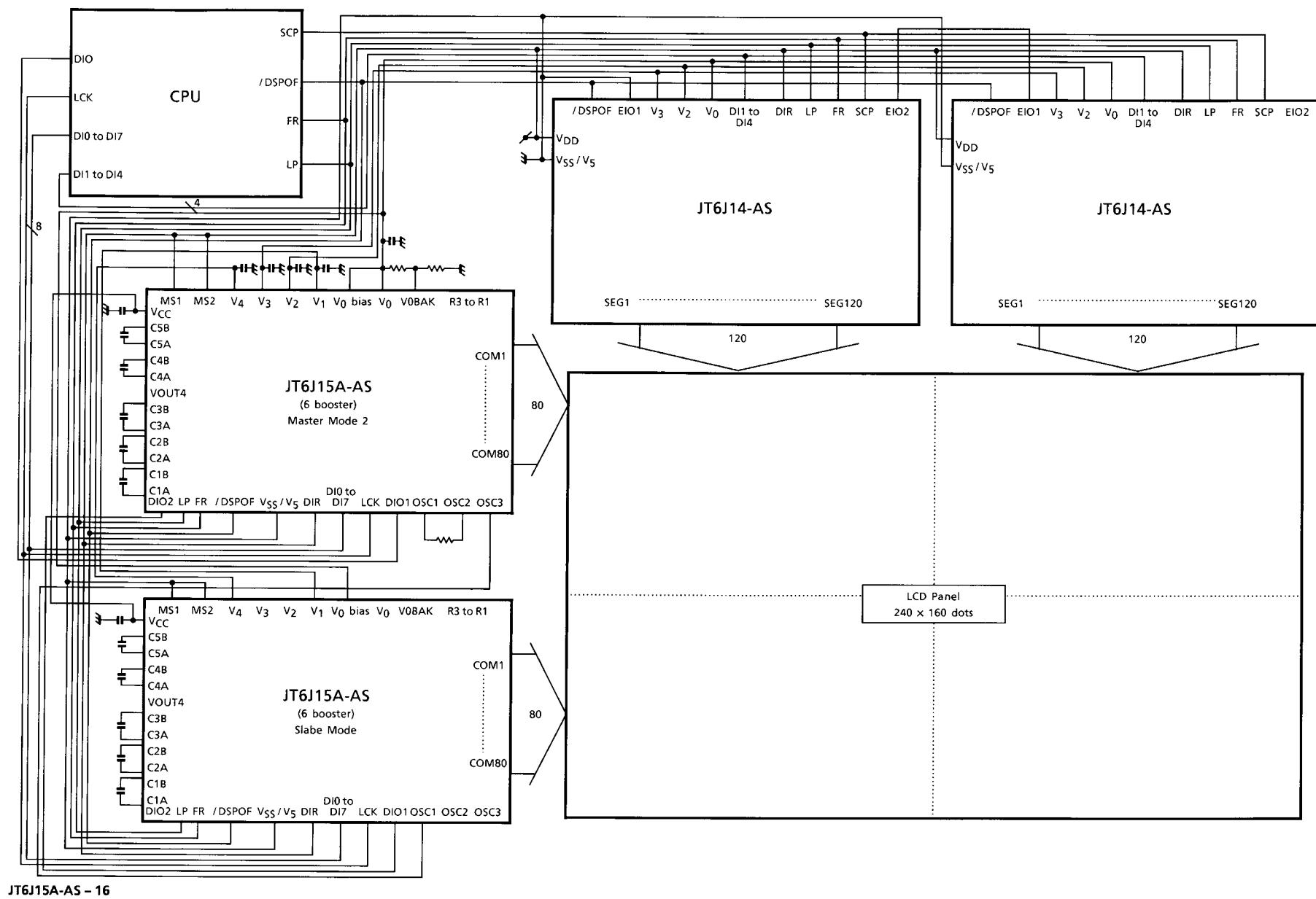
System Diagram (120 × 80 dots)



System Diagram (240 × 80 dots)



System Diagram (240 × 160 dots)



RESTRICTIONS ON PRODUCT USE

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- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
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- Light striking a semiconductor device generates electromotive force due to photoelectric effects. In some cases this can cause the device to malfunction.
This is especially true for devices in which the surface (back), or side of the chip is exposed. When designing circuits, make sure that devices are protected against incident light from external sources. Exposure to light both during regular operation and during inspection must be taken into account.
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